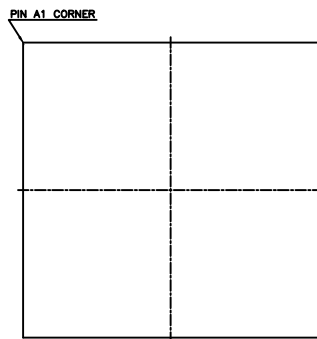
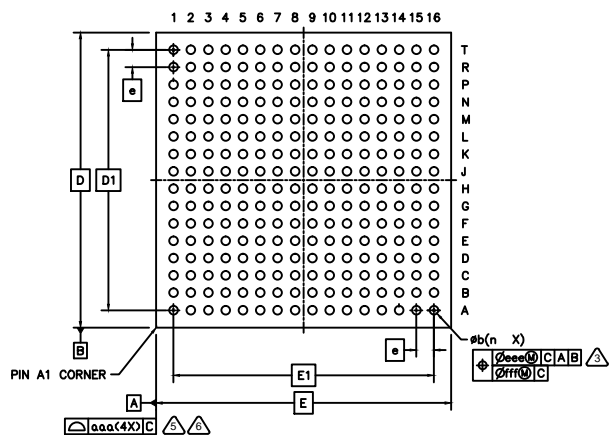
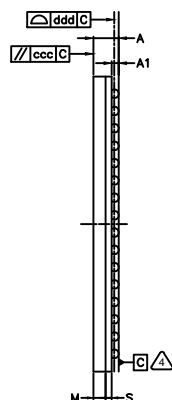




TOP VIEW



SIDE VIEW



BOTTOM VIEW

	Symbol	Common Dimensions		
		MIN.	NOM.	MAX.
Body Size:	X Y	E D	17.000	17.000
Ball Pitch:	e	1.000		
Total Thickness:	A	1.400	1.460	1.540
Mold Cap Thickness:	M	0.700 Ref.		
Substrate Thickness:	S	0.360 Ref.		
Ball Diameter:		0.500		
Stand Off:	A1	0.300	0.400	0.500
Ball Width:	b	0.450	0.500	0.550
Package Edge Tolerance:	aaa	0.200		
Mold Parallelism:	ccc	0.250		
Coplanarity:	ddd	0.200		
Ball Offset (Package):	eee	0.250		
Ball Offset (Ball):	fff	0.100		
Ball Count:	n	256		
Edge Ball Center to Center:	X Y	E1 D1	15.000	15.000

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\square C$.
- PRIMARY DATUM $\square C$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.14

Title: Package Outline Drawing	Pkg Type: CABGA	Document No: POD-250079	
Product Family: LFMXO4	Pin Count: 256		
Product Name: LFMXO4-015/025/050-BFG256	Pkg Size: 17x17 mm	Rev: A	
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